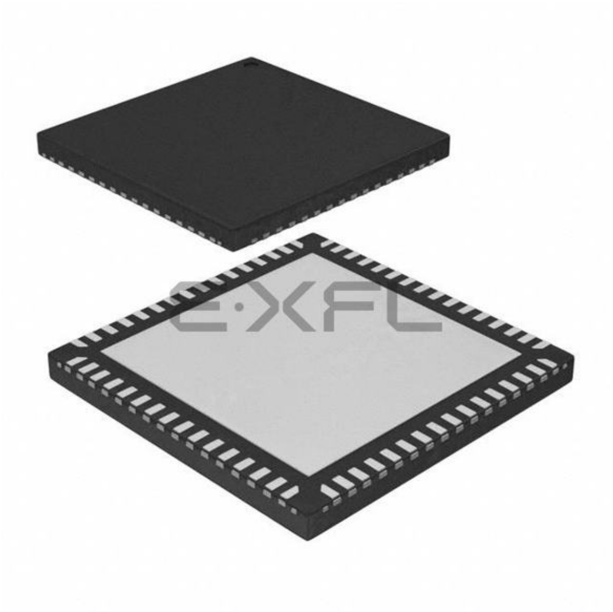
Microchip Technology - ATSAM3S4BA-MUR Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	64MHz
Connectivity	I²C, MMC, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	47
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	48K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 10x10/12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam3s4ba-mur

Figure 2-2. SAM3S 64-pin Version Block Diagram

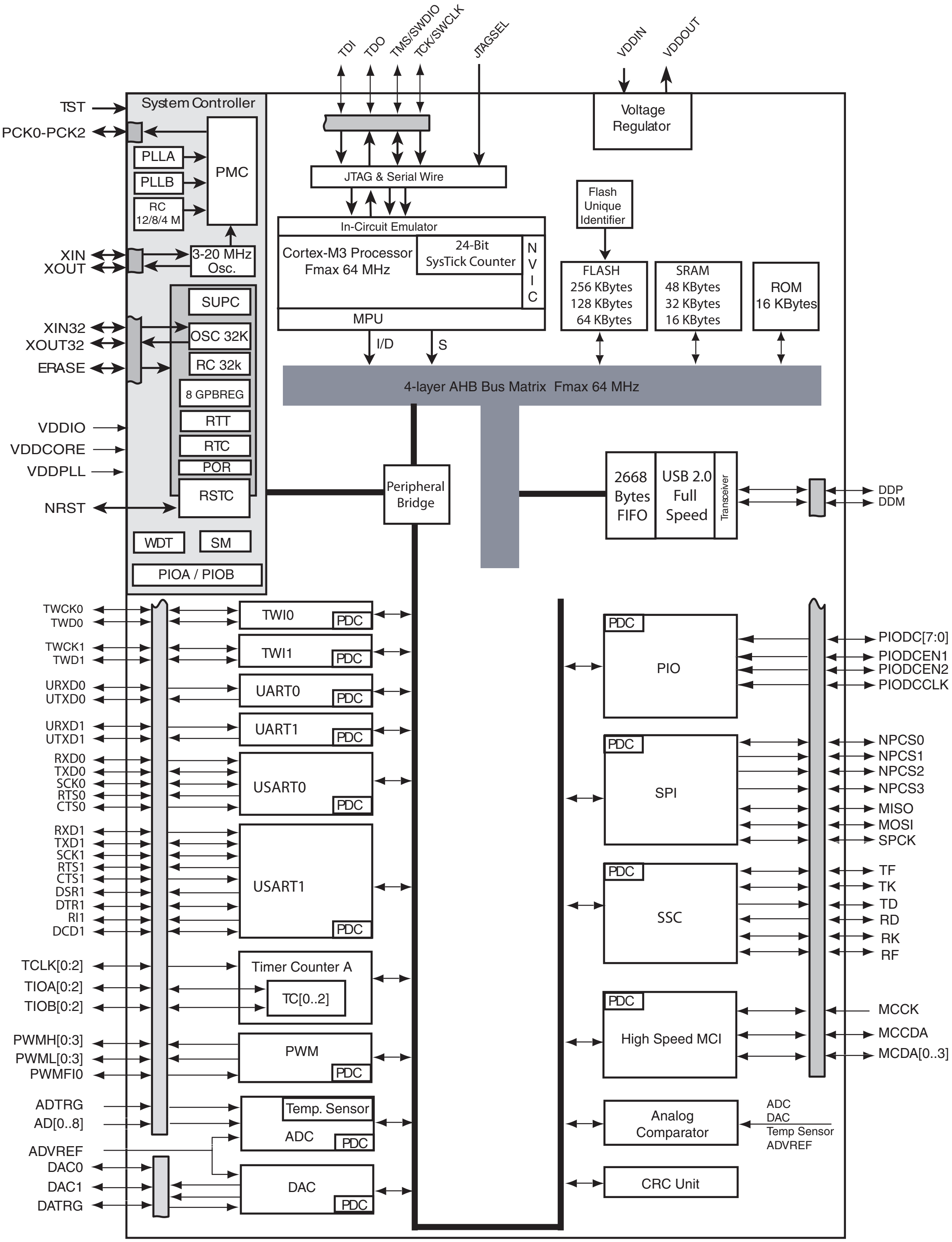


Figure 2-3. SAM3S 48-pin Version Block Diagram

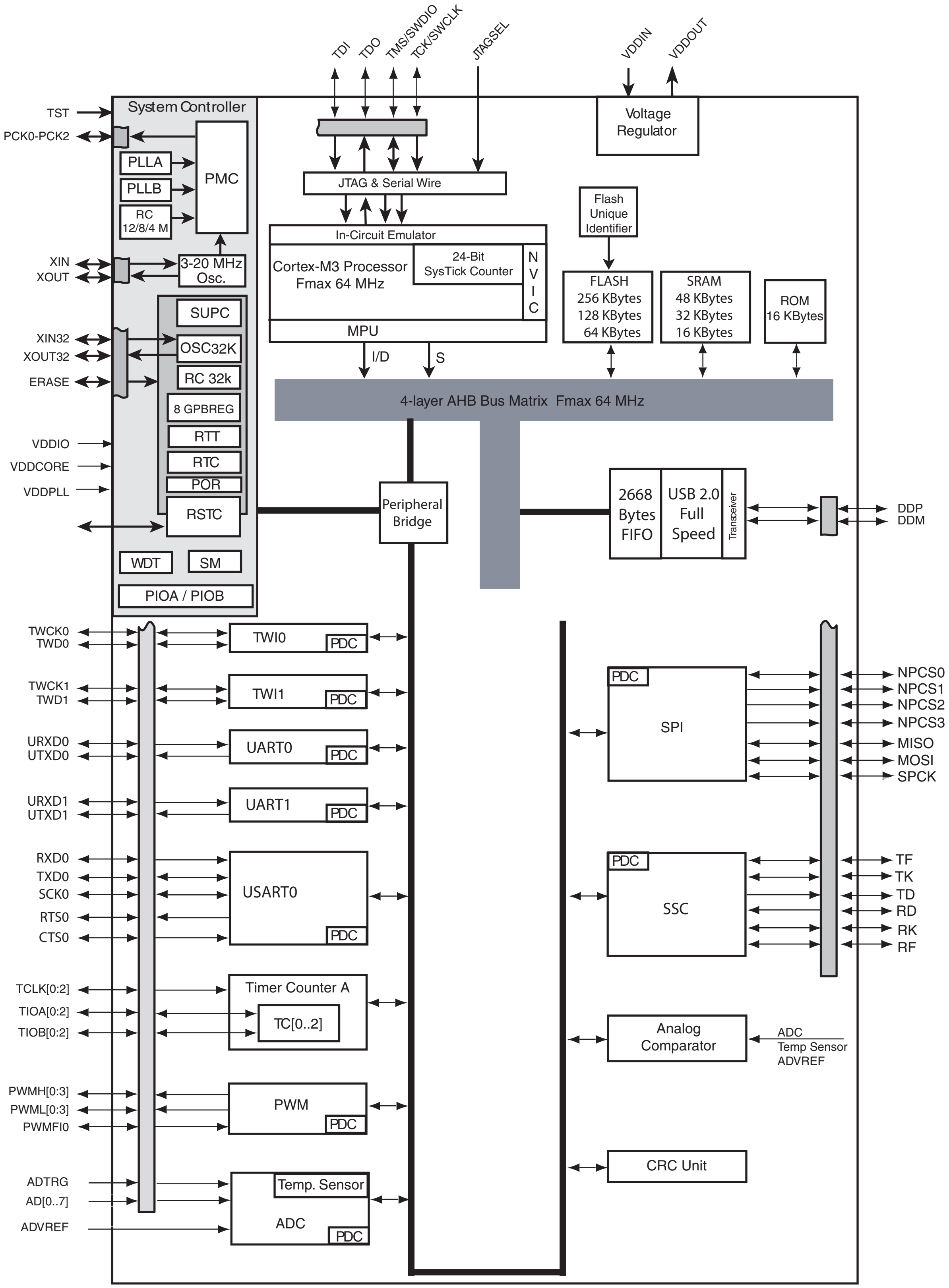


Table 3-1. Signal Description List (Continued)

Signal Name	Function	Type	Active Level	Voltage reference	Comments
Fast Flash Programming Interface - FFPI					
PGMEN0-PGMEN2	Programming Enabling	Input		VDDIO	
PGMM0-PGMM3	Programming Mode	Input		VDDIO	
PGMD0-PGMD15	Programming Data	I/O			
PGMRDY	Programming Ready	Output	High		
PGMNVALID	Data Direction	Output	Low		
PGMNOE	Programming Read	Input	Low		
PGMCK	Programming Clock	Input			
PGMNCMD	Programming Command	Input	Low		
USB Full Speed Device					
DDM	USB Full Speed Data -	Analog, Digital		VDDIO	Reset State: - USB Mode - Internal Pull-down(3)
DDP	USB Full Speed Data +				

Notes:
1. Schmitt Triggers can be disabled through PIO registers.
2. Some PIO lines are shared with System IOs.
3. Refer to the USB sub section in the product Electrical Characteristics Section for Pull-down value in USB Mode.
4. See Section 5.3 “Typical Powering Schematics” for restriction on voltage range of Analog Cells.

4.3 SAM3S4/2/1A Package and Pinout

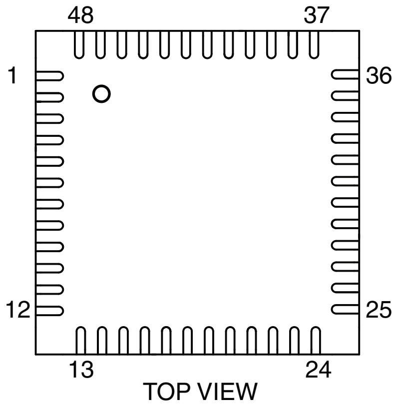


Figure 4-5. Orientation of the 48-pad QFN Package

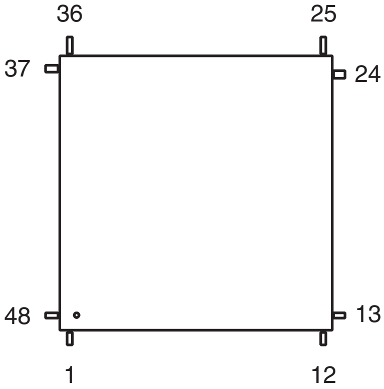


Figure 4-6. Orientation of the 48-lead LQFP Package

5. Power Considerations

5.1 Power Supplies

The SAM3S product has several types of power supply pins:

- VDDCORE pins: Power the core, the embedded memories and the peripherals; voltage ranges from 1.62V and 1.95V.
- VDDIO pins: Power the Peripherals I/O lines (Input/Output Buffers); USB transceiver; Backup part, 32kHz crystal oscillator and oscillator pads; ranges from 1.62V and 3.6V
- VDDIN pin: Voltage Regulator Input, ADC, DAC and Analog Comparator Power Supply; Voltage ranges from 1.8V to 3.6V
- VDDPLL pin: Powers the PLLA, PLLB, the Fast RC and the 3 to 20 MHz oscillator; voltage ranges from 1.62V and 1.95V.

5.2 Voltage Regulator

The SAM3S embeds a voltage regulator that is managed by the Supply Controller.

This internal regulator is intended to supply the internal core of SAM3S. It features two different operating modes:

- In Normal mode, the voltage regulator consumes less than 700 µA static current and draws 80 mA of output current. Internal adaptive biasing adjusts the regulator quiescent current depending on the required load current. In Wait Mode quiescent current is only 7 µA.

• In Backup mode, the voltage regulator consumes less than 1 µA while its output (VDDOUT) is driven internally to GND. The default output voltage is 1.80V and the start-up time to reach Normal mode is inferior to 100 µs.

For adequate input and output power supply decoupling/bypassing, refer to the Voltage Regulator section in the Electrical Characteristics section of the datasheet.

5.3 Typical Powering Schematics

The SAM3S supports a 1.62V-3.6V single supply mode. The internal regulator input connected to the source and its output feeds VDDCORE. Figure 5-1 shows the power schematics.

As VDDIN powers the voltage regulator, the ADC/DAC and the analog comparator, when the user does not want to use the embedded voltage regulator, it can be disabled by software via the SUPC (note that it is different from Backup mode).

- WKUPEN0-15 pins (level transition, configurable debouncing)
- Supply Monitor alarm
- RTC alarm
- RTT alarm

5.5.2 Wait Mode

The purpose of the wait mode is to achieve very low power consumption while maintaining the whole device in a powered state for a startup time of less than 10 µs. Current Consumption in Wait mode is typically 15 µA (total current consumption) if the internal voltage regulator is used or 8 µA if an external regulator is used.

In this mode, the clocks of the core, peripherals and memories are stopped. However, the core, peripherals and memories power supplies are still powered. From this mode, a fast start up is available.

This mode is entered via Wait for Event (WFE) instructions with LPM = 1 (Low Power Mode bit in PMC_FSMR). The Cortex-M3 is able to handle external events or internal events in order to wake-up the core (WFE). This is done by configuring the external lines WUP0-15 as fast startup wake-up pins (refer to Section 5.7 "Fast Startup"). RTC or RTT Alarm and USB wake-up events can be used to wake up the CPU (exit from WFE).

Entering Wait Mode:

- Select the 4/8/12 MHz fast RC oscillator as Main Clock
- Set the LPM bit in the PMC Fast Startup Mode Register (PMC_FSMR)
- Execute the Wait-For-Event (WFE) instruction of the processor

Note: Internal Main clock resynchronization cycles are necessary between the writing of MOSCRCEN bit and the effective entry in Wait mode. Depending on the user application, Waiting for MOSCRCEN bit to be cleared is recommended to ensure that the core will not execute undesired instructions.

5.5.3 Sleep Mode

The purpose of sleep mode is to optimize power consumption of the device versus response time. In this mode, only the core clock is stopped. The peripheral clocks can be enabled. The current consumption in this mode is application dependent.

This mode is entered via Wait for Interrupt (WFI) or Wait for Event (WFE) instructions with LPM = 0 in PMC_FSMR.

The processor can be woke up from an interrupt if WFI instruction of the Cortex M3 is used, or from an event if the WFE instruction is used to enter this mode.

5.5.4 Low Power Mode Summary Table

The modes detailed above are the main low power modes. Each part can be set to on or off separately and wake up sources can be individually configured. Table 5-1 below shows a summary of the configurations of the low power modes.

Table 5-1. Low Power Mode Configuration Summary

Mode	SUPC, 32 kHz Oscillator RTC RTT Backup Registers, POR (Backup Region)	Regulator	Core Memory Peripherals	Mode Entry	Potential Wake Up Sources	Core at Wake Up	PIO State while in Low Power Mode	PIO State at Wake Up	Consumption [2] [3]	Wake-up Time[1]
Backup Mode	ON	OFF	OFF (Not powered)	WFE +SLEEPDEEP bit = 1	WUP0-15 pins SM alarm RTC alarm RTT alarm	Reset	Previous state saved	PIOA & PIOB & PIOC Inputs with pull ups	3 µA typ[4]	< 0.1 ms
Wait Mode	ON	ON	Powered (Not clocked)	WFE +SLEEPDEEP bit = 0 +LPM bit = 1	Any Event from: Fast startup through WUP0-15 pins RTC alarm RTT alarm USB wake-up	Clocked back	Previous state saved	Unchanged	5 µA/15 µA [5]	< 10 µs
Sleep Mode	ON	ON	Powered[7] (Not clocked)	WFE or WFI +SLEEPDEEP bit = 0 +LPM bit = 0	Entry mode =WFI Interrupt Only; Entry mode =WFE Any Enabled Interrupt and/or Any Event from: Fast start-up through WUP0-15 pins RTC alarm RTT alarm USB wake-up	Clocked back	Previous state saved	Unchanged	[6]	[6]

Notes:

1. When considering wake-up time, the time required to start the PLL is not taken into account. Once started, the device works with the 4/8/12 MHz fast RC oscillator. The user has to add the PLL start-up time if it is needed in the system. The wake-up time is defined as the time taken for wake up until the first instruction is fetched.
2. The external loads on PIOs are not taken into account in the calculation.
3. Supply Monitor current consumption is not included.
4. Total Current consumption.
5. 5 µA on VDDCORE, 15 µA for total current consumption (using internal voltage regulator), 8 µA for total current consumption (without using internal voltage regulator).
6. Depends on MCK frequency.
7. In this mode the core is supplied and not clocked but some peripherals can be clocked.

6. Input/Output Lines

The SAM3S has several kinds of input/output (I/O) lines such as general purpose I/Os (GPIO) and system I/Os. GPIOs can have alternate functionality due to multiplexing capabilities of the PIO controllers. The same PIO line can be used whether in IO mode or by the multiplexed peripheral. System I/Os include pins such as test pins, oscillators, erase or analog inputs.

6.1 General Purpose I/O Lines

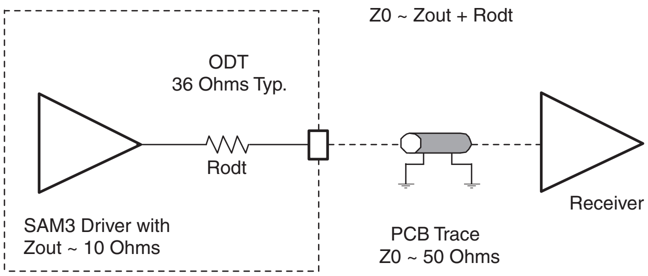
GPIO Lines are managed by PIO Controllers. All I/Os have several input or output modes such as pull-up or pull-down, input Schmitt triggers, multi-drive (open-drain), glitch filters, debouncing or input change interrupt. Programming of these modes is performed independently for each I/O line through the PIO controller user interface. For more details, refer to the product PIO controller section.

The input output buffers of the PIO lines are supplied through VDDIO power supply rail.

The SAM3S embeds high speed pads able to handle up to 32 MHz for HSMCI (MCK/2), 45 MHz for SPI clock lines and 35 MHz on other lines. See AC Characteristics Section in the Electrical Characteristics Section of the datasheet for more details. Typical pull-up and pull-down value is 100 kΩ for all I/Os.

Each I/O line also embeds an ODT (On-Die Termination), see Figure 6-1. It consists of an internal series resistor termination scheme for impedance matching between the driver output (SAM3S) and the PCB trace impedance preventing signal reflection. The series resistor helps to reduce IOs switching current (di/dt) thereby reducing in turn, EMI. It also decreases overshoot and undershoot (ringing) due to inductance of interconnect between devices or between boards. In conclusion ODT helps diminish signal integrity issues.

Figure 6-1. On-Die Termination



6.2 System I/O Lines

System I/O lines are pins used by oscillators, test mode, reset and JTAG to name but a few. Described below are the SAM3S system I/O lines shared with PIO lines:

These pins are software configurable as general purpose I/O or system pins. At startup the default function of these pins is always used.

Table 6-1. System I/O Configuration Pin List.

SYSTEM_IO bit number	Default function after reset	Other function	Constraints for normal start	Configuration
12	ERASE	PB12	Low Level at startup(1)	In Matrix User Interface Registers (Refer to the SystemIO Configuration Register in the Bus Matrix section of the product datasheet.)
10	DDM	PB10	-	
11	DDP	PB11	-	
7	TCK/SWCLK	PB7	-	
6	TMS/SWDIO	PB6	-	
5	TDO/TRACESWO	PB5	-	
4	TDI	PB4	-	
-	PA7	XIN32	-	See footnote (2) below
-	PA8	XOUT32	-	
-	PB9	XIN	-	See footnote (3) below
-	PB8	XOUT	-	

Notes:
1. If PB12 is used as PIO input in user applications, a low level must be ensured at startup to prevent Flash erase before the user application sets PB12 into PIO mode,
2. In the product Datasheet Refer to: Slow Clock Generator of the Supply Controller section.
3. In the product Datasheet Refer to: 3 to 20 MHZ Crystal Oscillator information in PMC section.

6.2.1 Serial Wire JTAG Debug Port (SWJ-DP) Pins

The SWJ-DP pins are TCK/SWCLK, TMS/SWDIO, TDO/SWO, TDI and commonly provided on a standard 20-pin JTAG connector defined by ARM. For more details about voltage reference and reset state, refer to Table 3-1 on page 6.

At startup, SWJ-DP pins are configured in SWJ-DP mode to allow connection with debugging probe. Please refer to the Debug and Test Section of the product datasheet.

SWJ-DP pins can be used as standard I/Os to provide users more general input/output pins when the debug port is not needed in the end application. Mode selection between SWJ-DP mode (System IO mode) and general IO mode is performed through the AHB Matrix Special Function Registers (MATRIX_SFR). Configuration of the pad for pull-up, triggers, debouncing and glitch filters is possible regardless of the mode.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. It integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

By default, the JTAG Debug Port is active. If the debugger host wants to switch to the Serial Wire Debug Port, it must provide a dedicated JTAG sequence on TMS/SWDIO and TCK/SWCLK which disables the JTAG-DP and enables the SW-DP. When the Serial Wire Debug Port is active, TDO/TRACESWO can be used for trace.

The asynchronous TRACE output (TRACESWO) is multiplexed with TDO. So the asynchronous trace can only be used with SW-DP, not JTAG-DP. For more information about SW-DP and JTAG-DP switching, please refer to the Debug and Test Section.

6.3 Test Pin

The TST pin is used for JTAG Boundary Scan Manufacturing Test or Fast Flash programming mode of the SAM3S series. The TST pin integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations. To enter fast programming mode, see the Fast Flash Programming Interface (FFPI) section. For more on the manufacturing and test mode, refer to the “Debug and Test” section of the product datasheet.

6.4 NRST Pin

The NRST pin is bidirectional. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. It will reset the Core and the peripherals except the Backup region (RTC, RTT and Supply Controller). There is no constraint on the length of the reset pulse and the reset controller can guarantee a minimum pulse length. The NRST pin integrates a permanent pull-up resistor to VDDIO of about 100 kΩ. By default, the NRST pin is configured as an input.

6.5 ERASE Pin

The ERASE pin is used to reinitialize the Flash content (and some of its NVM bits) to an erased state (all bits read as logic level 1). It integrates a pull-down resistor of about 100 kΩ to GND, so that it can be left unconnected for normal operations.

This pin is debounced by SCLK to improve the glitch tolerance. When the ERASE pin is tied high during less than 100 ms, it is not taken into account. The pin must be tied high during more than 220 ms to perform a Flash erase operation.

The ERASE pin is a system I/O pin and can be used as a standard I/O. At startup, the ERASE pin is not configured as a PIO pin. If the ERASE pin is used as a standard I/O, startup level of this pin must be low to prevent unwanted erasing. Please refer to Section 11.2 “Peripheral Signal Multiplexing on I/O Lines” on page 43. Also, if the ERASE pin is used as a standard I/O output, asserting the pin to low does not erase the Flash.

7. Processor and Architecture

7.1 ARM Cortex-M3 Processor

- Version 2.0
- Thumb-2 (ISA) subset consisting of all base Thumb-2 instructions, 16-bit and 32-bit
- Harvard processor architecture enabling simultaneous instruction fetch with data load/store
- Three-stage pipeline
- Single cycle 32-bit multiply
- Hardware divide
- Thumb and Debug states
- Handler and Thread modes
- Low latency ISR entry and exit

7.2 APB/AHB bridge

The SAM3S product embeds one peripheral bridge:

The peripherals of the bridge are clocked by MCK.

7.3 Matrix Masters

The Bus Matrix of the SAM3S product manages 4 masters, which means that each master can perform an access concurrently with others, to an available slave.

Each master has its own decoder, which is defined specifically for each master. In order to simplify the addressing, all the masters have the same decodings.

Table 7-1. List of Bus Matrix Masters

Master 0	Cortex-M3 Instruction/Data
Master 1	Cortex-M3 System
Master 2	Peripheral DMA Controller (PDC)
Master 3	CRC Calculation Unit

7.4 Matrix Slaves

The Bus Matrix of the SAM3S product manages 5 slaves. Each slave has its own arbiter, allowing a different arbitration per slave.

Table 7-2. List of Bus Matrix Slaves

Slave 0	Internal SRAM
Slave 1	Internal ROM
Slave 2	Internal Flash
Slave 3	External Bus Interface
Slave 4	Peripheral Bridge

Table 7-4. Peripheral DMA Controller (Continued)

Instance Name	Channel T/R	100 & 64 Pins	48 Pins
UART0	Receive	x	x
USART1	Receive	x	x
USART0	Receive	x	x
ADC	Receive	x	x
SPI	Receive	x	x
SSC	Receive	x	x
HSMCI	Receive	x	N/A
PIOA	Receive	x	x

7.7 Debug and Test Features

- Debug access to all memory and registers in the system, including Cortex-M3 register bank when the core is running, halted, or held in reset.
- Serial Wire Debug Port (SW-DP) and Serial Wire JTAG Debug Port (SWJ-DP) debug access
- Flash Patch and Breakpoint (FPB) unit for implementing breakpoints and code patches
- Data Watchpoint and Trace (DWT) unit for implementing watchpoints, data tracing, and system profiling
- Instrumentation Trace Macrocell (ITM) for support of printf style debugging
- IEEE1149.1 JTAG Boundary-can on All Digital Pins

9. Memories

9.1 Embedded Memories

9.1.1 Internal SRAM

The ATSAM3S4 product (256-Kbyte internal Flash version) embeds a total of 48 Kbytes high-speed SRAM.

The ATSAM3S2 product (128-Kbyte internal Flash version) embeds a total of 32 Kbytes high-speed SRAM.

The ATSAM3S1 product (64-Kbyte internal Flash version) embeds a total of 16 Kbytes high-speed SRAM.

The SRAM is accessible over System Cortex-M3 bus at address 0x2000 0000.

The SRAM is in the bit band region. The bit band alias region is mapped from 0x2200 0000 to 0x23FF FFFF.

9.1.2 Internal ROM

The SAM3S product embeds an Internal ROM, which contains the SAM Boot Assistant (SAM-BA), In Application Programming routines (IAP) and Fast Flash Programming Interface (FFPI).

At any time, the ROM is mapped at address 0x0080 0000.

9.1.3 Embedded Flash

9.1.3.1 Flash Overview

The Flash of the ATSAM3S4 (256-Kbytes internal Flash version) is organized in one bank of 1024 pages (Single plane) of 256 bytes.

The Flash of the ATSAM3S2 (128-Kbytes internal Flash version) is organized in one bank of 512 pages (Single plane) of 256 bytes.

The Flash of the ATSAM3S1 (64-Kbytes internal Flash version) is organized in one bank of 256 pages (Single plane) of 256 bytes.

The Flash contains a 128-byte write buffer, accessible through a 32-bit interface.

9.1.3.2 Flash Power Supply

The Flash is supplied by VDDCORE.

9.1.3.3 Enhanced Embedded Flash Controller

The Enhanced Embedded Flash Controller (EEFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped on the APB.

The Enhanced Embedded Flash Controller ensures the interface of the Flash block with the 32-bit internal bus. Its 128-bit wide memory interface increases performance.

The user can choose between high performance or lower current consumption by selecting either 128-bit or 64-bit access. It also manages the programming, erasing, locking and unlocking sequences of the Flash using a full set of commands.

10.14 UART

- Two-pin UART
  - Implemented features are 100% compatible with the standard Atmel USART
  - Independent receiver and transmitter with a common programmable Baud Rate Generator
  - Even, Odd, Mark or Space Parity Generation
  - Parity, Framing and Overrun Error Detection
  - Automatic Echo, Local Loopback and Remote Loopback Channel Modes
  - Support for two PDC channels with connection to receiver and transmitter

10.15 PIO Controllers

- 3 PIO Controllers, PIOA, PIOB and PIOC (100-pin version only) controlling a maximum of 79 I/O Lines
- Fully programmable through Set/Clear Registers

Table 10-2. PIO available according to pin count

Version	48 pin	64 pin	100 pin
PIOA	21	32	32
PIOB	13	15	15
PIOC	-	-	32

- Multiplexing of four peripheral functions per I/O Line
- For each I/O Line (whether assigned to a peripheral or used as general purpose I/O)
  - Input change, rising edge, falling edge, low level and level interrupt
  - Debouncing and Glitch filter
  - Multi-drive option enables driving in open drain
  - Programmable pull-up or pull-down on each I/O line
  - Pin data status register, supplies visibility of the level on the pin at any time
- Synchronous output, provides Set and Clear of several I/O lines in a single write

11.2.1 PIO Controller A Multiplexing

Table 11-2. Multiplexing on PIO Controller A (PIOA)

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PA0	PWMH0	TIOA0	A17	WKUP0		High drive
PA1	PWMH1	TIOB0	A18	WKUP1		High drive
PA2	PWMH2	SCK0	DATRG	WKUP2		High drive
PA3	TWD0	NPCS3				High drive
PA4	TWCK0	TCLK0		WKUP3		
PA5	RXD0	NPCS3		WKUP4		
PA6	TXD0	PCK0				
PA7	RTS0	PWMH3			XIN32	
PA8	CTS0	ADTRG		WKUP5	XOUT32	
PA9	URXD0	NPCS1	PWMFI0	WKUP6		
PA10	UTXD0	NPCS2				
PA11	NPCS0	PWMH0		WKUP7		
PA12	MISO	PWMH1				
PA13	MOSI	PWMH2				
PA14	SPCK	PWMH3		WKUP8		
PA15	TF	TIOA1	PWML3	WKUP14/PIODCEN1		
PA16	TK	TIOB1	PWML2	WKUP15/PIODCEN2		
PA17	TD	PCK1	PWMH3	AD0		
PA18	RD	PCK2	A14	AD1		
PA19	RK	PWML0	A15	AD2/WKUP9		
PA20	RF	PWML1	A16	AD3/WKUP10		
PA21	RXD1	PCK1		AD8		64/100-pin versions
PA22	TXD1	NPCS3	NCS2	AD9		64/100-pin versions
PA23	SCK1	PWMH0	A19	PIODCCLK		64/100-pin versions
PA24	RTS1	PWMH1	A20	PIODC0		64/100-pin versions
PA25	CTS1	PWMH2	A23	PIODC1		64/100-pin versions
PA26	DCD1	TIOA2	MCDA2	PIODC2		64/100-pin versions
PA27	DTR1	TIOB2	MCDA3	PIODC3		64/100-pin versions
PA28	DSR1	TCLK1	MCCDA	PIODC4		64/100-pin versions
PA29	RI1	TCLK2	MCCK	PIODC5		64/100-pin versions
PA30	PWML2	NPCS2	MCDA0	WKUP11/PIODC6		64/100-pin versions
PA31	NPCS1	PCK2	MCDA1	PIODC7		64/100-pin versions

11.2.2 PIO Controller B Multiplexing

Table 11-3. Multiplexing on PIO Controller B (PIOB)

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PB0	PWMH0			AD4		
PB1	PWMH1			AD5		
PB2	URXD1	NPCS2		AD6/ WKUP12		
PB3	UTXD1	PCK2		AD7		
PB4	TWD1	PWMH2			TDI	
PB5	TWCK1	PWML0		WKUP13	TDO/TRACESWO	
PB6					TMS/SWDIO	
PB7					TCK/SWCLK	
PB8					XOUT	
PB9					XIN	
PB10					DDM	
PB11					DDP	
PB12	PWML1				ERASE	
PB13	PWML2	PCK0		DAC0		64/100-pin versions
PB14	NPCS1	PWMH3		DAC1		64/100-pin versions

12. Embedded Peripherals Overview

12.1 Serial Peripheral Interface (SPI)

- Supports communication with serial external devices
  - Four chip selects with external decoder support allow communication with up to 15 peripherals
  - Serial memories, such as DataFlash and 3-wire EEPROMs
  - Serial peripherals, such as ADCs, DACs, LCD Controllers, CAN Controllers and Sensors
  - External co-processors
- Master or slave serial peripheral bus interface
  - 8- to 16-bit programmable data length per chip select
  - Programmable phase and polarity per chip select
  - Programmable transfer delays between consecutive transfers and between clock and data per chip select
  - Programmable delay between consecutive transfers
  - Selectable mode fault detection
- Very fast transfers supported
  - Transfers with baud rates up to MCK
  - The chip select line may be left active to speed up transfers on the same device

12.2 Two Wire Interface (TWI)

- Master, Multi-Master and Slave Mode Operation
- Compatibility with Atmel two-wire interface, serial memory and I^2C compatible devices
- One, two or three bytes for slave address
- Sequential read/write operations
- Bit Rate: Up to 400 kbit/s
- General Call Supported in Slave Mode
- Connecting to PDC channel capabilities optimizes data transfers in Master Mode only
  - One channel for the receiver, one channel for the transmitter
  - Next buffer support

12.3 Universal Asynchronous Receiver Transceiver (UART)

- Two-pin UART
  - Independent receiver and transmitter with a common programmable Baud Rate Generator
  - Even, Odd, Mark or Space Parity Generation
  - Parity, Framing and Overrun Error Detection
  - Automatic Echo, Local Loopback and Remote Loopback Channel Modes
  - Support for two PDC channels with connection to receiver and transmitter

- Programmable gain: 1, 2, 4

12.11 Digital-to-Analog Converter (DAC)

- Up to 2 channel 12-bit DAC
- Up to 2 mega-samples conversion rate in single channel mode
- Flexible conversion range
- Multiple trigger sources for each channel
- 2 Sample/Hold (S/H) outputs
- Built-in offset and gain calibration
- Possibility to drive output to ground
- Possibility to use as input to analog comparator or ADC (as an internal wire and without S/H stage)
- Two PDC channels
- Power reduction mode

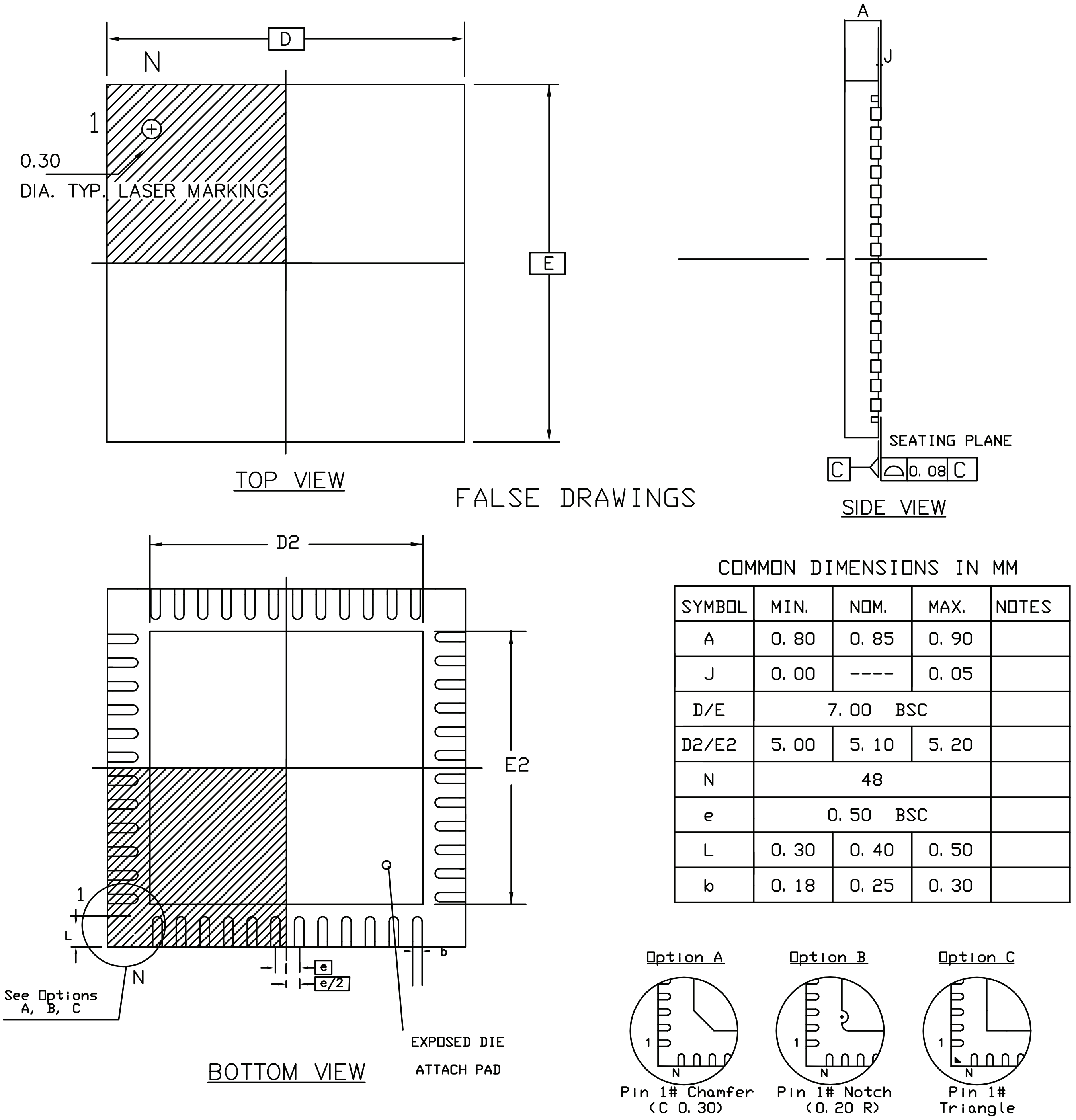
12.12 Static Memory Controller

- 16-Mbyte Address Space per Chip Select
- 8- bit Data Bus
- Word, Halfword, Byte Transfers
- Programmable Setup, Pulse And Hold Time for Read Signals per Chip Select
- Programmable Setup, Pulse And Hold Time for Write Signals per Chip Select
- Programmable Data Float Time per Chip Select
- External Wait Request
- Automatic Switch to Slow Clock Mode
- Asynchronous Read in Page Mode Supported: Page Size Ranges from 4 to 32 Bytes
- NAND FLASH additional logic supporting NAND Flash with Multiplexed Data/Address buses
- Hardware Configurable number of chip select from 1 to 4
- Programmable timing on a per chip select basis

12.13 Analog Comparator

- One analog comparator
- High speed option vs. low power option
- Selectable input hysteresis:
  - 0, 20 mV, 50 mV
- Minus input selection:
  - DAC outputs
  - Temperature Sensor
  - ADVREF
  - AD0 to AD3 ADC channels
- Plus input selection:
  - All analog inputs

Figure 13-4. 48-pad QFN Package



COMMON DIMENSIONS IN MM

SYMBOL	MIN.	NOM.	MAX.	NOTES
A	0.80	0.85	0.90	
J	0.00	----	0.05	
D/E	7.00 BSC			
D2/E2	5.00	5.10	5.20	
N	48			
e	0.50 BSC			
L	0.30	0.40	0.50	
b	0.18	0.25	0.30	

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